



Material Content Data Sheet



Sales Product Name		TLE4253GS		Issued		25. January 2018		
MA#		MA001370036						
Package		PG-DSO-8-46		Weight*		83.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.205	2.66	2.66	26551	26551
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		436	
	non noble metal	iron	7439-89-6	0.723	0.87		8711	
wire	non noble metal	copper	7440-50-8	29.372	35.37	36.29	353722	362978
	non noble metal	copper	7440-50-8	0.069	0.08	0.08	832	832
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1165
encapsulation	plastics	epoxy resin	-	4.450	5.36		53587	
	inorganic material	silicondioxide	60676-86-0	43.819	52.78	58.26	527718	582470
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9924	9924
plating	noble metal	silver	7440-22-4	0.144	0.17	0.17	1736	1736
glue	plastics	epoxy resin	-	0.322	0.39		3877	
	noble metal	silver	7440-22-4	0.966	1.16	1.55	11632	15509
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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